FRONT VIEW

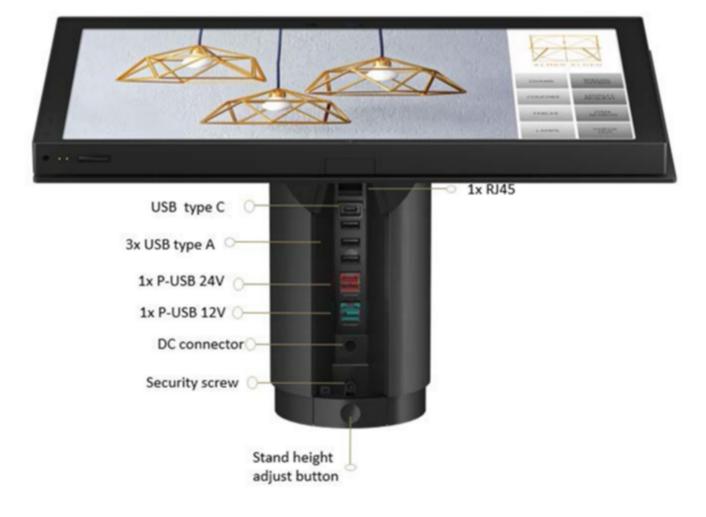




REAR VIEW

HP Engage One Pro Column hub

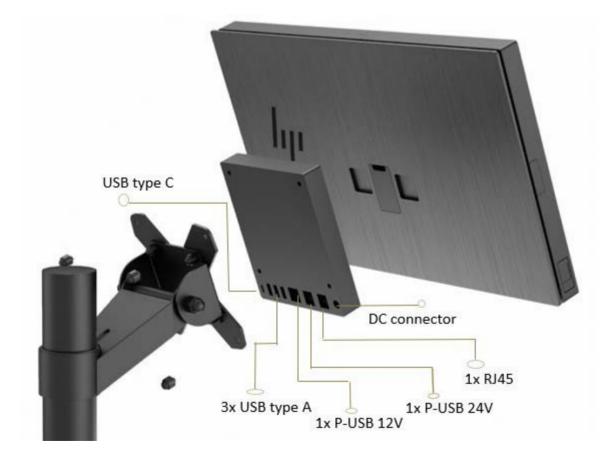




IMPORTANT: To avoid damage to the computer, DO NOT plug a telephone cable into t

HP Engage One Pro VESA hub





IMPORTANT: To avoid damage to the computer, DO NOT plug a telephone cable into t

HP Engage One Pro Advanced Fan-less Hub



IMPORTANT: To avoid damage to the computer, DO NOT plug a telephone cable into t

	Component Breakdown
1.	Head unit: Choice of 3 screen sizes: 15.6"?, 19.5"?, 23.8"?. Landscape or portrait orientation
2.	Stand: Choice of 4: Performance stand, Pro stand, Vertical stand, Slim VESA wall mount

Not shown: Head unit connects with hub through a 140W Cable with secure screwed to connectivity base

Overview



Component Breakdown

Overview



HP Engage One Pro Stand Features



1. Performance Stand-Height adjustable 50mm, tilt 40⁰ -120⁰

2. Engage One Pro sta

Stand Configurations

*NOTE: HP Engage One Pro & HP Engage One Pro Vertical stand can be configured in the same way as the Performance stand shown in



HP Engage One Pro AiO Slim VESA wall mount (100x100mm)

HP Engage One Pro AiO Performance* Stand Clean Counter Mount No stability plate-include



HP Engage One Pro AiO Performance* stand with Stability Base Plate

Overview



HP Engage One Pro AiO System Performance* stand with Stability Base Plate-Hub attached

At A Glance

- Choice of 2 colors: Ebony Black & Ceramic White* *White only available in 15.6"?
- Choice of 2 orientations: Landscape & portrait
- Landscape Choice of with or without Camera
- Choice of 3 Long lifecycle performance All-in-One (AiO) Retail System for retail and hospitality markets ope
 15.6" diagonal, FHD (1920 x 1080), touch, IPS, UWVA, anti-glare, 400 nits, 45% NTSC
 - 19.5" diagonal, FHD (1920 x 1080), touch, VA, UWVA, anti-glare, 450 nits, 72% NTSC
 - 23.8" diagonal, FHD (1920 x 1080), touch, IPS, UWVA, anti-glare, 625 nits, 72% NTSC Note: Actual brightness will be lower with touch screen
- Choice of 3 column stand:
 - HP Engage One Pro Performance stand
 - HP Engage One Pro stand
 - HP Engage One Pro Vertical stand
- Choice of Mounting:
 - Clean counter- Place the connectivity hub under the counter
 - All together- Place the hub directly under the stand
 - Slim VESA wall mount- Place the head unit on the wall
 - Pole mount- -Place the head unit on a single or back-to-back pole
- Intel® Q470E chipset, 65W Processors
- Processor choices:
 - o 10th Generation Intel[®] CoreTM i9 processor
 - o 10th Generation Intel[®] Core[™] i7 processor
 - o 10th Generation Intel $^{\circ}$ CoreTM i5 processor
 - o 10th Generation Intel $^{\circ}$ CoreTM i3 processor
 - o Intel® Pentium® processor
 - o Intel® Celeron® processor
 - o Integrated: Intel® UHD Graphics 610 on Celeron & Pentium; Intel® UHD Graphics 630 on i3 to i9
 - o 16GB Intel® OptaneTM Memory H10 with Solid State Storage
 - o Intel® Ethernet Connection I219LM GbE LOM integrated network connection
 - o Intel[®] Wi-Fi 6 AX201 (2x2) and Bluetooth[®] 5 combo, non-vPro[®] Intel[®] Wi-Fi 6 AX201 (2x2) and Bluetooth[®] 5 combo, vf
- Operating System choices:
 - Windows 10 Pro 64-bit Windows 10 IoT Enterprise 2019 LTSC 64
 - FreeDOS 2.0
 - SUSE Linux[®] Enterprise Desktop 12 (certification only)
 - Android 11
- Connectivity Base Choices
 - HP Engage One Column hub:
 - HP Engage One VESA hub
 - HP Engage One Advanced Fan-less hub
- Integrated peripheral options (can also be purchased and installed separately)
- HP Engage One Pro MSR
- HP Engage One Pro Bar Code Scanner (choose between 3 locations: left, right, bottom) of the head unit
- HP Engage One Pro Fingerprint Reader

Overview

- HP Engage One Pro 6x6 Customer facing display with 2x20 line display emulation **
 **The 2x20 line display emulation can be used on 6.6"? CFD and future CFDs for Engage One Pro Virtual Line Display will wor
 size line display such as 3x16 or 3x20, 5x10
- Virtual Line Display will work with any display. It defaults to 2x20,, it can also be used for any other size line display such as 3
- Industry-standard 100mm VESA mounting pattern allows for flexible use without the optional stand (Mounting hardware sold
- (2) Two DDR4 Memory Slots (32 GB Maximum)
- Realtek RTL8153 AH Ethernet Connection
- Intel & Realtek WLAN Options
- Trusted Platform Module (TPM 2.0)
- HP BIOSphere with HP Sure Start technology
- Cable Management Features
- ENERGY STAR[®] certified configurations available, EU Compliant, RoHS2 Compliant, EPEAT[®] registered configurations available
- Standard Warranty Options 90/90/90, 1/1/1, 3/3/3; Plus Optional Care Packs
- 32 GB DDR4-2666 SDRAM Transfer rates up to 2666 MT/s.
- 2 SODIMM Memory slots
- 1 M.2 expansion slot
- 2xM.2 Storage slots
- 128 GB to up to 1 TB PCIe[®] NVMe[™] SSD
- 128 GB to up to 1 TB PCIe[®] NVMe[™] SSD
- 256 GB to up to 512 GB PCIe[®] NVMe[™] SS
- Integrated HD audio with Realtek ALC3247 codec with standards internal speakers and stereo headphone j
- HP Credential Guard; HP Device Guard; HP Support Assistant; HP BIOSphere with Sure Start Generation (
- HP Sure Sense; HP Sure Click (Standard); HP Sure Admin; HP MIK (SCCM Integration); HP Image Assista Security Manager Gen7; HP Sure Recover Gen3; HP Sure Run Gen3
- Intel® vPro® with AMT 11.0; TPM 2.0; HP System Software Manager; HP Image Assistant; HP Client Securi
- Display head Ports and Connectors: 1 audio-out; 2 SuperSpeed USB Type-A 5Gbps signaling rate; 2 Super Sleep and Charge); 1 RJ-45 USB NIC; 1 140W data port Side: 1 Security lock slot
- Choice of 3 connectivity hubs:

• HP Engage One Pro Column hub:

- 3 SuperSpeed USB Type-A 5Gbps signaling rate
- 1 RJ-45 NIC
- 1 DC connector
- 2 USB 2.0 Type-A
- 1 SuperSpeed USB Type-C® 5Gbps signaling rate (27 W Power Delivery, Alt Mode DisplayPort^T
- 1x 140W data port
- 1x P-USB 12V
- 1x P-USB 24V

• HP Engage One Pro VESA hub:

- 3 SuperSpeed USB Type-A 5Gbps signaling rate
- 1 RJ-45 NIC
- 1 DC connector
- 2 USB 2.0 Type-A
- 1 SuperSpeed USB Type-C® 5Gbps signaling rate (27 W Power Delivery, Alt Mode DisplayPort^T
- 1 140W data port
- 1x P-USB 12V
- 1x P-USB 24V

o HP Engage One Pro Advance fan-less hub

- 1 cash drawer connector
- 3 USB Type-A; 2 power serials
- 4 SuperSpeed USB Type-A 10Gbps signaling rate, 1 RJ-45 NIC
- 1 DC connector
- 1 SuperSpeed USB Type-C® 5Gbps signaling rate (27 W Power Delivery, Alt Mode DisplayPort^T
- 1 x140W data port]

- 2x P-USB 12V
- 1x P-USB 24V
- Combination of Advance hub with Column hub; Combination of Advance hub with VESA hub.

NOTE: See important legal disclosures for all listed specs in their respectiv

SECURITY DISCLAIMERS:

HP Essential Security requires Windows 10, includes various HP Sure security features and is available on HP Elite and Workstation pr HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. Not available on platforms with multipl videos, etc. before using HP Sure Recover to avoid loss of data. HP Sure Recover Gen3 requires an open network connection. You mus loss of data.

HP Sure Start Gen6 is available on select HP PCs.

HP Sure Click is only supported on Intel Core i3, i5, i7 and i9 processors.

HP Sure Click, Sure Run, Sure Recover & Sure Sense is supported on Win 10 Pro & Win 10 IoT Enterprise 2019 LTSC; but not on Win 10 For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on

Features

OPERATING SYSTEM

Preinstalled	Windows 10 Pro 64-bit ¹ Windows 10 IoT Enterprise 2019 LTSC 64 FreeDOS 3.0 Android 11
Certified	SUSE Linux [®] Enterprise Desktop ²
NOTE:	

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com
- SUSE Enterprise Linux 15 SP2 YES Certification on a single platform configuration. More information about SUSE YES certification on https://http://www.suse.com/partners/ihv/yes/ The following features are not supported by SUSE Linux Enterprise Desktop:
- Power Management features
- Multi-touch capabilities
- Systems configured with Linux do not qualify for ENERGY STAR®

Adapters and Cables

- HP USB-C® to DisplayPort
- HP USB-C® to HDMI
- HP USB-C® to VGA
- USB to Serial Port Adapter

NETWORKING/COMMUNICATIONS

- Intel® I219-LM Gigabit Network Connection LOM (standard)
- Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 vPro, supporting gigabitdata rate)*, **
- Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 non-vPro, supporting gigabit data rate)*, **
- Realtek RTL8822CE 802.11ac 2x2 Wi-Fi® + BT5***

*Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

** Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.

***Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

Features

NEAR FIELD COMMUNICATION

WNC XRAV-1 NFC

PORTS

HP Engage One Pro Head unit I/O:

- 1x 140W data port (PDO cable to Head Unit)¹
- 1x RJ45 vPro NIC
- 1x UAJ (Audio jack)
- 4x Integrated USB-A Gen1 Peripherals ports
- 2x USB3.2 G1 Type-A / 900mA
- 2x USB3.2 G1 Type-A / 2.2A

Internal access door for the SSD and USB-Port Type A on Motherboard

Dimensions for USB-Port Type A:

55mm L includes plug / 16mm W / 8mm

HP Engage One Pro Column hub I/O

- 3x USB3.2 G2 Type-A / 900mA
- 1x RJ45 (cable direct from Head unit)
- 1x DC connector
- 1x P-USB 12V
- 1x P-USB 24V
- 1x USB3.2 G1 Type-C® DP Alt Mode / 27W
- 1x 140W data port (PDO cable to Head Unit)¹

HP Engage One Pro VESA hub I/O

- 3x USB3.1 G1 Type-A / 900mA
- 1x RJ45 (cable direct from Head unit)
- 1x DC connector
- 1x P-USB 12V
- 1x P-USB 24V
- 1x USB3.2 G1 Type-C® DP Alt Mode / 27W
- 1x 140W data port (PDO cable to Head Unit) ¹

HP Engage One Pro Advanced Fan-less hub I/O

- 1x RJ12 Cash Drawer
- 2x 12V P-USB
- 1x 24V P-USB
- 2x DB9 P-Serial
- 4x USB3.2 G1 Type A/900mA
- 1x RJ45 USB NIC
- 1x DC connector
- 1x USB3.1 G2 Type-C® DP Alt Mode / 27W
- 1x 140W data port (PDO cable to Head Unit) ¹

NOTE 1: HP 140W port only compatible with the 140W cable included with the product. Cable required for the HP Engage One Pro to operate

Features

USB SPECIFICATION

Speed	Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1

SOFTWARE COMPONENTS AND APPLICATIONS

BIOS

• HP BIOSphere Gen6

- Protect and manage the foundation of your POS System
- Building on over a decade of BIOS security leadership, HP BIOSphere Gen6 offers an ecosystem of protections to help defend your system, including automated protections, customizable safeguards, and easy manageability
- HP Secure Erase¹
- Device Guard Enablement

Additional features of the HP BIOS Features

Power-On password

Software

- HP Privacy Settings
- HP Setup Integrated OOBE
- HP Easy Clean²
- HP Notifications
- myHP

Manageability Features

- HP Driver Packs
- HP Manageability Integration Kit³
- HP Image Assistant
- HP Smart Support⁴
 - Notes:
- 1. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® OptaneTM.
- 2. HP Easy Clean requires Windows and will disable the keyboard, display and touchpad only. Ports are not disabled.
- 3. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
- 4. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

Features

Security Management

- HP BIOSphere Gen 6¹
- HP Client Security Manager Gen7⁶
- HP Multi-Factor Authenticate -
- HP SpareKey -
- HP Sure Start⁶
- HP Sure Run⁴ -
- HP Sure Recover⁴-Recover quickly and minimize downtime
 - Driven by the HP Endpoint Security Controller, HP Sure Recover enables users to reimage their systems quickly and securely using only a network connection no IT intervention needed.

Other Security Features

- HP Engage One AiO System Biometric Fingerprint Reader (optional)
- Bolt to counter mechanism
- VESA mounting
- Keyed Cable Lock
- Trusted Platform Module TPM 2.0
- Drive lock
- USB enable/disable (via BIOS)
- Power-on password (via BIOS)
- Setup password (via BIOS)
- Tamper Resistant Screw affixed on stand of the system unit, used to secure display head to stand without Quick Released
- HP vPRO Support

Notes:

- 1. HP BIOSphere Gen6 features may vary depending on the platform and configuration.
- 2. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation
- agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be
 purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolut
 Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:
 http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service
 provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data
- 4. HP Sure Click, Sure Run, Sure Recover & Sure Sense is supported on Win 10 Pro & Win 10 IoT Enterprise 2019 LTSC; but not on Win 10 IoT Enterprise 2016 LTSB.
- 5. HP Client Security Manager Gen7 requires Windows
- 6. HP Sure Start Gen6 is available on select HP PCs.

Technical Specifications

PROCESSORS

- Intel® Celeron® G5900E with Intel® UHD Graphics 610 (3.2 GHz base frequency, 2 MB L3 cache, 2 cores)
- Intel® Pentium® Gold G6400E with Intel® UHD Graphics 610 (3.8 GHz base frequency, 4 MB L3 cache, 2 cores) Intel® CoreTM i3-10100E with Intel® UHD Graphics 630 (3.2 GHz base frequency, up to 3.8 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores) ²
- Intel® CoreTM i7-10700E with Intel® UHD Graphics 630 (2.9 GHz base frequency, up to 4.5 GHz with Intel® Turbo Boost Technology, 16 MB L3 cache, 8 cores), supports Intel® vPro® Technology 3
- Intel® CoreTM i9-10900E with Intel® UHD Graphics 630 (2.8 GHz base frequency, up to 4.7 GHz with Intel® Turbo Boost Technology, 20 MB L3 cache, 10 cores), supports Intel® vPro® Technology 3
- Intel® CoreTM i5-10500E with Intel® UHD Graphics 630 (3.1 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores), supports Intel® vPro® Technology 3

PROCESSORS FAMILY

10th Gen 65W Intel CoreTM processors

NOTES:

- 1. Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a mea configuration surement of higher performance.
- 2. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies

depending on hardware, software and overall system. See http://http://www.intel.com/technology/turboboost for more information.

3. For full Intel® vPro® functionality, Windows 10 Pro 64 bit, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or WLAN card and TPM 2.0 are required. Some functionality requires additional 3rd party software in order to run. See http://intel.com/vpro

INTEL® 10th GENERATION CORETM vPRO ® PROCESSORS

Intel® CoreTM i5-10500E with Intel® UHD Graphics 630 (3.1 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores), supports Intel® vPro® Technology

Intel® CoreTM i7-10700E with Intel® UHD Graphics 630 (2.9 GHz base frequency, up to 4.5 GHz with Intel® Turbo Boost Technology, 16 MB L3 cache, 8 cores), supports Intel® vPro® Technology

Intel® CoreTM i9-10900E with Intel® UHD Graphics 630 (2.8 GHz base frequency, up to 4.7 GHz with Intel® Turbo Boost Technology, 20 MB L3 cache, 10 cores), supports Intel® vPro® Technology 3

The HP Engage One Pro AiO System Retail System features this technology and includes processors that are part of the Intel® Stable Image. Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP Engage One Pro AiO System Retail System.

Technical Specifications

Intel® Advanced Management Technology (AMT) v11.6+

An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state.

- AMT 11.6+ includes the following advanced management function
- Power Management (on, off, reset
- Hardware Inventory (includes BIOS and firmware revisions
- Hardware Alerting
- Agent Presence
- System Defense Filters
- SOL/USBR
- Cisco NAC/SDN Support
- ME Wake-on-LAN DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the PC connects to the IT or service provider console for maintenance. Remote PCs can get required patches, be inventoried, etc. by connecting to their IT console or Service Provider when it's convenient
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host-based set-up and configuration
- Management Engine (ME) firmware roll back
- Wireless AMT functionality on Desktop (WoDT)
- Enhanced KVM resolution

*Some functionality of this technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vProTM technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances"? is yet to be determined.

** Intel® Active Management Technology requires an Intel® AMT-enabled chipset, network hardware and software, as well as connection with a power source and a corporate network connection. Setup requires configuration by the purchaser and may require scripting with the management console or further integration into existing security frameworks to enable certain functionality. It may also require modifications of implementation of new business processes.

OPERATOR DISPLAY*

15.6" Diagonal Wide Aspect, Projective Capacitive, Anti-glare, Anti-smudge, IPS Display

Touch Technology	Projected Capacitive Touchscreen
Resolution	1920 x 1080
Aspect Ratio	16:9
Max Color	16.2M
Brightness	Typical 400 Nits*
Contrast Ratio	Typical 800:1
Pixel Pitch	0.17925 x 0.17925mm

Technical Specifications

Viewing Angle	Horizontal 178°, Vertical 178°
Response rate	25ms (Typical On / Off)
Backlight	LED
Operating Temperature range	0 to 50°C (+ 50°C as panel surface temperature)

19.5" Diagonal Wide Aspect, Projective Capacitive, Anti-glare, Anti-smudge, UWVA, IPS Display

Touch Technology	Projected Capacitive Touchscreen
Resolution	1920 x 1080
Aspect Ratio	16:9
Max Color	16.7M
Brightness	Typical 450 Nits*
Contrast Ratio	Typical 2000:1
Pixel Pitch	0.2265 x 0.2210mm
Viewing Angle	Horizontal 170°, Vertical 170°
Response rate	25ms (Typical On / Off)
Backlight	LED
Operating Temperature range	0 to 50°C (+ 50°C as panel surface temperature)

23.8" Diagonal Wide Aspect, Projective Capacitive, Anti-glare, Anti-smudge, IPS Display

Touch Technology	Projected Capacitive Touchscreen
Resolution	1920 x 1080
Aspect Ratio	16:9
Max Color	16.7M
Brightness	Typical 625 Nits*
Contrast Ratio	1000:1
Pixel Pitch	274.5 um x 2274.5 um
Viewing Angle	Horizontal 178°, Vertical 178°
Response rate	14ms (Typical On / Off)
Backlight	LED
Operating Temperature range	0 to 50°C (+ 50°C as panel surface temperature)

***NOTE:** Nits is the measure of the typical brightness of the panel as specified, prior to anti-glare coating ***NOTES:**

Portrait Display.With a Portrait Head Unit, the pre-OS environment will be displayed 90° in Landscape.

Once the Windows OS loads, then the display will show Portrait.

*All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Technical Specifications-Graphics

Intel[®] HD Graphics (integrated)

Integrated Graphics

Intel® UHD Graphics 630 (integrated on 10th gen Core i9/i7/i5/i3 Intel® UHD Graphics 610 (integrated on 10th gen Pentium® G6400E, Celeron® G5900E)

DisplayPort

DisplayPort over the optional USB-C® module

Memory

The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use

Maximum Graphic Memory

Windows 10 >6 GB

Maximum Color Depth

64bits/pixel 10th Generation Intel® CoreTM processors:

 Next Generation Intel[®] Clear Video Technology HD Support is a collection of video playback and

enhancement features that improve the end user's viewing experience

- o Encode/transcode HD content
- o Playback of high-definition content including Blu-ray Disc
- o Superior image quality with sharper, more colorful images

Graphics/Video API Support

- DirectX Video Acceleration (DXVA) support for accelerating video processing o Full AVC/VC1/MPEG2/HEVC HW Decode
- Advanced Scheduler 2.0, 1.0
- Windows 10, Linux OS Support
- O DirectX 12.1
- OpenGL 4.4
- Open CL 1.2 (Intel[®] HD Graphics 630)
- Open CL 1.2/2.0 (Intel[®] HD Graphics 610)

NOTE: the actual amount of maximum graphics memory can be less than the amounts listed above depending upon your computer's configuration.

Supported Display Resolutions and Refresh Rates

Note: Other resolutions may be available but are not recommended as they may not have been tested and qualified by HP

Technical Specifications-Graphics

Resolution	Refresh Rate
640x480	60Hz640x48067Hz
640x480	72Hz
640x480	75Hz
720x400	70Hz
800x600	60Hz
800x600	75Hz
1024x768	60Hz
1024x768	75Hz
1280x960	60Hz
1280x720	60Hz
1280x1024	60Hz
1280x1024	75Hz
1440x900	60Hz
1440x900	75Hz
1680x1050	60Hz
1920x1080	60Hz
3440x1440	60Hz 3440x144030Hz
2048x1536	60Hz
4096x2160	60Hz
4096x2160	60Hz

Technical Specifications-Memory

MEMORY

Туре

DDR4-2666 SDRA Transfer rates up to 2666 MT/s **Maximum**

32 GB

of Slots

2 SODIMM

Memory Upgrades

- 4GB (1x4GB) DDR4 2666 SODIMM Memory
- 8GB (1x8GB) DDR4 2666 SODIMM Memory
- 16GB (2x8GB) DDR4 2666 SODIMM Memory
- 16GB (1x16GB) DDR4 2666 SODIMM Memory
- 32GB (2x16GB) DDR4 2666 SODIMM Memory

NOTE: Memory speed 2666 and 2933 MT/s can be achieved via two SODIMMs per channel (2DPC) when populated with the same part number.

System Memory Support

The HP Engage One Pro AiO System Retail System supports DDR4 protocols with two independent, 64-bit wide channels eacl accessing one or two SoDIMMs.

- Two channels of non-ECC DDR4 unbuffered small outline dual in-line memory modules (SO-DIMM) with a maximum of one DIMMs per channel
- Single-channel and dual-channel memory organization modes Data burst length of eight for all memory organization modes
- Memory data transfer rates of up to 2400 MT/s; actual supported data transfer rate determined by the configured processor.
- 64-bit wide channels
- DDR4 system memory I/O voltage of 1.2V
- Theoretical maximum memory bandwidth of:
- 21.3 GB/s in dual-channel mode assuming 1333 MT/s
- 25.6 GB/s in dual-channel mode assuming 1600 MT/s
- 34.0 GB/s in dual-channel mode assuming 2133 MT/s
- 38.4 GB/s in dual-channel mode assuming 2400 MT/s

Key Benefits of DDR4 Memory:

- Dual channel configuration HP Engage One Pro AiO System features motherboards designed with two memory channels instead of a single channel.
- Reduce system latencies and significantly improve your system performance with dual channel memory configuration by utilizing the theoretical bandwidth of two memory modules instead of one.
- Expect fast start-up times with reduced delays during routine operations and system maintenance functions. Meet everyday workloads head on and run more programs simultaneously. Easily toggle back and forth between several open applications with noticeable speed.

Notes

For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system. Memory modules support data transfer rates up to 2400 MT/s; actual data rate is determined by the system's configured processor. See processor specifications for supported memory data rate.

CAUTION: You must shut down the Retail System and disconnect the power cord before adding or removing memory modules. Regardless of the power-on state, voltage is always supplied to the memory modules as long as the Retail System is plugged in to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board.

SOLID STATE STORAGE

Drive Bays: (2) M.2 PCIe x4 2280/2230 Combo (for storage)

PCIe NMVe Solid State Drives (SSD)¹

- 128GB 2280 PCIe-3x2 TLC Solid State Drive
- 256GB M.2 2280 PCIe NVMe SED OPAL2 TLC Solid State Drive
- 256GB M.2 2280 PCIe NVMe TLC Solid State Drive
- 256GB Intel Optane Memory H10 with Solid State Storage²
- 512GB M.2 2280 PCIe NVMe TLC Solid State Drive
- 512GB Intel Optane Memory H10 with Solid State Storage²
- TTB 2280 PCIe-3x4 NVMe TLC Solid State Drive Storage accelerator
- NVMe RAID 1

Notes:

- 1. Storage DriveLock does not work with Self-Encrypting or Optane based storage
- 2. Intel[®] OptaneTM memory system acceleration does not replace or increase the DRAM in your system.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Unformatted Capacity	128GB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Unformatted Capacity	256GB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Unformatted Capacity	512GB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

1TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Unformatted Capacity	1TB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 3480MB/s
Maximum Sequential Write	Up to3037MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Unformatted Capacity	1TB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 3480MB/s
Maximum Sequential Write	Up to3037MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

Technical Specifications-Storage

256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Unformatted Capacity	256GB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256GB Intel[®] PCIe[®] NVMe[™] QLC + 32GB Intel[®] Optane[™]

Unformatted Capacity	256GB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 1450MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

512GB Intel® PCIe® NVMe[™] QLC + 32GB Intel® Optane[™]

Unformatted Capacity	512GB
Interface	PCle Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 2400MB/s
Maximum Sequential Write	Up to 1300MB/s
Logical Blocks	1,000,215,215
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1TB 2280 PCIe-3x4 NVMe TLC Solid State Drive

Unformatted Capacity	1TB
Interface	PCIe Gen 3
Form Factor	M.2
Height	2.38mm
Width	22mm
Length	80mm
Weight	<10g
Maximum Sequential Read	Up to 3480MB/s
Maximum Sequential Write	Up to 3037MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
	0° to 70°C (32° to 158°F) [ambient temp]

Networking/Communications

Ethernet (RJ-45)

• Intel[®] I219-LM Gigabit Network Connection LOM (standard)

Wireless

- Intel[®] Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 vPro, supporting gigabit data rate)*, **
- Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 non-vPro, supporting gigabit data rate)*, **
- Realtek RTL8822CE 802.11ac 2x2 Wi-Fi[®] + BT5***

Notes:

NIC Fundamentals:

By default, the HP BIOS set the HUB WOL setting to disabled state, which will not allow wake signal from the USB bus to initiate a wake event. On Engage One Plus, the Embedded Lan Controller is enabled by default and is what HP recommend using as the primary nic for WOL capability as seen in the BIOS F10 menu If customer has a reason to use the HUB NIC and wants to wake the system from that NIC. They must enable wake events for the HUB to get the functionality.

*Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.

** Wi-Fi 5 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels. ***Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

Connector	RJ-45	
System Interface	PCI (Intel proprietary) + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling(Hash Mode Only) Jumbo Frame 9K	
Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW Wo Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW	

Power Management	ACPI compliant - multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from modem standby or sleep state (Magic Packet and Microsoft Wake-Up Frame) Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel [®] vPro TM support with appropriate Intel [®] chipset components

Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11ax		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Features Wi-Fi 6 technology		
Frequency Band	802.11b/g/n/ax		
	• 2.402 - 2.482 GHz		
	• 2.402 - 2.482 GHZ 802.11a/n/ac/ax		
	802.11d/11/dC/dX		
	• 4.9 - 4.95 GHz (Japan)		
	• 5.15 - 5.25 GHz		
	• 5.25 - 5.35 GHz		
	• 5.47 - 5.725 GHz		
	• 5.825 - 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 		
	 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 		
	• $802.11n$: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	 802.11ac : MCS 0 ~ MCS 9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 		
	• 802.11aC . MCS0 ~ MCS9, (1SS, and 2SS) (200002, 400002, 800002 & 1600002)		
	 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, 80MHz 		
Madulation	<u>& 160MHz)</u>		
Modulation	Direct Sequence Spread Spectrum		
Cocuritu ³	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM		
Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 		

•			
		x authentication	
		WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
		2 certification	
	 IEEE 802. 	11i	
	WAPI		
Network Architecture Models	Ad-hoc (Peer to Pe	eer)	
		cess Point Required)	
Roaming		liant roaming between access points	
Output Power ²		+18.5dBm minimum	
output i owei		+17.5dBm minimum	
		+18.5dBm minimum	
		IT20(2.4GHz) : +15.5dBm minimum	
		IT40(2.4GHz) : +14.5dBm minimum	
		IT20(5GHz) : +15.5dBm minimum	
	● 802.11n F	IT40(5GHz) : +14.5dBm minimum	
	• 802.1	1ac VHT80(5GHz) : +11.5dBm minimum	
	• 802.1	1ac VHT160(5GHz) : +11.5dBm minimum	
	• 802.1	1ax HT40(2.4GHz) : +10dBm minimum	
		1ax VHT160(5GHz) : +10dBm minimum	
Power Consumption		mit mode: 2.0 W	
		ive mode: 1.6 W	
		node (PSP) 180 mW (WLAN Associated)	
		node: 50 mW (WLAN unassociated)	
		ected Standby: 10mW	
		disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant	power saving mode	
Receiver Sensitivity ³	• 802.11b,	1Mbps : -93.5dBm maximum	
	• 802.11b,	11Mbps : -84dBm maximum	
		1a/g, 6Mbps : -86dBm maximum	
		1a/g, 54Mbps : -72dBm maximum	
		1n, MCS07 : -67dBm maximum	
	 802.11n, MCS07 : -67dBin maximum 802.11n, MCS15 : -64dBm maximum 		
	 802.11ac, MCS0 : -84dBm maximum 		
	• 802.11ac, MCS9 : -59dBm maximum		
	• 802.11ax, MCS11(HT40): -59dBm maximum		
		MCS11(VHT160): -58.5dBm maximum	
Antenna type		tenna with spatial diversity, mounted in the display enclosure	
		ial band 2.4/5 GHz antennas are provided to the card to support WLAN MIM	
		and Bluetooth communications	
Form Factor	PCI-Express M.2 M	liniCard with CNVi Interface	
Dimensions	1. Type 2230 : 2.3	v 22.0 v 20.0 mm	
		7 x 12.0 x 16.0 mm	
Waight			
Weight	1. Type 2230 : 2.8	y .	
On eventing Valte as	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (-10° to 70° C)	
· ciriperature	Non-operating	-40° to 176° F (-40° to 80° C)	
Humiditu	Operating		
Humidity		10% to 90% (non-condensing)	
A1.1. I	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber - Radi	o OFF; LED White - Radio ON	

HP Integrated Module with Bluetooth^â 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth ^â Specification	4.0/4.1/4.2/5.0/5.1 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels.
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetoothâ component shall operate as a Class II Bluetoothâ device with a maximum transmit power of +9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW
-	Selective Suspend 17 mW
Bluetooth ^â Software Supported Link Topology	Microsoft Windows Bluetoothâ Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudgin Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro TM support with appropriate Intel® chipset components

Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11ax
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k

	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Features Wi-Fi 6 technology		
Frequency Band	802.11b/g/n/ax		
	• 2.402 - 2.482 GHz		
	802.11a/n/ac/ax		
	• 4.9 - 4.95 GHz (Japan)		
	• 5.15 - 5.25 GHz		
	• 5.25 - 5.35 GHz		
	• 5.47 - 5.725 GHz		
- - - -	• 5.825 - 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz		
	& 160MHz)		
	 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 		
Modulation	Direct Sequence Spread Spectrum		
Modulation	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM		
	ט אין א אין אין אין אין אין אין אין אין א		
Security3	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only 		
	AES-CCMP: 128 bit in hardware		
	802.1x authentication		
	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. 		
	WPA2 certification		
	• IEEE 802.11i		
	WAPI		
Network Architecture Models	Ad-hoc (Peer to Peer)		
	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power2	• 802.11b : +18.5dBm minimum		
-	 802.11g : +17.5dBm minimum 		
	• 802.11a : +18.5dBm minimum		
	 802.11n HT20(2.4GHz) : +15.5dBm minimum 		
	 802.11n HT40(2.4GHz) : +14.5dBm minimum 		
	 802.11n HT20(5GHz) : +15.5dBm minimum 		
	 802.11n HT40(5GHz) : +14.5dBm minimum 		
	 802.11ac VHT80(5GHz) : +11.5dBm minimum 		
	 802.11ac VHT160(5GHz) : +11.5dBm minimum 		
	 802.11ax HT40(2.4GHz) : +10dBm minimum 		
	 802.11ax VHT160(5GHz) : +10dBm minimum 		
Power Consumption	Transmit mode 2.0 W		
	Receive mode 1.6 W		
	Idle mode (PSP) 180 mW (WLAN Associated)		
	Idle mode 50 mW (WLAN unassociated)		
	Connected Standby 10mW		
	Radio disabled 8 mW		
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		

Receiver Sensitivity3		1Mbps : -93.5dBm maximum	
		11Mbps : -84dBm maximum	
	• 802.	11a/g, 6Mbps : -86dBm maximum	
	• 802.	11a/g, 54Mbps : -72dBm maximum	
	• 802.	11n, MCS07 : -67dBm maximum	
		11n, MCS15 : -64dBm maximum	
		11ac, MCS0 : -84dBm maximum	
		11ac, MCS9 : -59dBm maximum	
		k, MCS11(HT40): -59dBm maximum	
		k, MCS11(VHT160): -58.5dBm maximum	
Antenna type	High efficiency a	ntenna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIN		
	communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface		
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm		
	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g		
	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (-10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber - Rad	lio OFF; LED Off - Radio ON	
HP Integrated Module with Bluetooth ^â			
Bluetooth ^â Specification	4.0/4.1/4.2/5.0/5	4.0/4.1/4.2/5.0/5.1 Compliant	
Frequency Band	2402 to 2480 MH		
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)		
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps		
2.	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps		
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels.		
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) (864 kbps symmetric (3-EV5)		
Transmit Dower	The Bluetoothâ component shall operate as a Class II Bluetoothâ device with a maximum		
Transmit Dower	I ho Bluotootha c	יייוואטוופווג אומנג טאפרמנפ מצ מ כנמצצ זו פונופנטטנוומ עפעוכפ אונוו מ וומצווועווו.	
Transmit Power		of +9.5 dBm for BR and EDR.	
Transmit Power Power Consumption	transmit power o	of +9.5 dBm for BR and EDR. N Peak (Rx) 230 mW	
Transmit Power Power Consumption	transmit power o	N Peak (Rx) 230 mW	
	transmit power of Peak (Tx) 330 mV Selective Suspen	N Peak (Rx) 230 mW	

Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822CE 802.1	lac 2x2 Wi-Fi + BT5
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
	IEEE 802.11d
	IEEE 802.11e
	IEEE 802.11h
	IEEE 802.11i
	IEEE 802.11k
	IEEE 802.11r
	IEEE 802.11v
Interoperability	Wi-Fi [®] certified
Frequency Band	802.11b/g/n
	• 2.402 - 2.482 GHz
	802.11a/n/ac
	• 4.9 - 4.95 GHz (Japan)
	• 5.15 - 5.25 GHz
	• 5.25 - 5.35 GHz
	• 5.47 - 5.725 GHz
	• 5.825 - 5.850 GHz
Data Datas	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ³	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g
	mode only
	AES-CCMP: 128 bit in hardware
	802.1x authentication
	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i

Technical Specifications – Networking and Communications

WAPI Network Architecture Models Ad-hoc (Peer to Peer)				
	Infrastructure (Access Point Required)			
Roaming	IEEE 802.11 compliant roaming between access points			
Output Power ²	• 802.11b : +18.5dBm minimum			
		: +17.5dBm minimum		
	j ū	: +18.5dBm minimum		
		HT20(2.4GHz) : +15.5dBm minimum		
		HT40(2.4GHz) : +14.5dBm minimum		
		HT20(5GHz) : +15.5dBm minimum		
		HT40(5GHz) : +14.5dBm minimum		
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum			
		11ac VHT160(5GHz) : +11.5dBm minimum		
Power Consumption	1	smit mode :2.0 W		
rower consumption		sine mode :2.0 W		
		node (PSP) 180 mW (WLAN Associated)		
		node :50 mW (WLAN unassociated)		
		nected Standby/Modern Standby: 10mW		
		o disabled: 8 mW		
Dower Management		ress compliant power management		
Power Management		t power saving mode		
		power saving mode		
Receiver Sensitivity3	802.11b, 1Mbps :	-93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps		
	-86dBm maximur	n 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximu		
802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.				
	59dBm maximum			
Antenna type	pe High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WL communications and Bluetooth communications			
	communications	and Bluetooth communications		
Form Factor	PCI-Express M.2 I	MiniCard with CNVi Interface		
 .				
Dimensions		3 x 22.0 x 30.0 mm 7 x 12.0 x 16.0 mm		
	2. Type 1216: 1.6	7 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8	3q		
-	2. Type 126: 1.3g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
	Non-operating	5% to 95% (non-condensing)		
	Operating	0 to 10,000 ft (3,048 m)		
Altitude	Operating			
Altitude	Non-operating	0 to 50,000 ft (15,240 m)		

r Integrated Module with Bluetooth" 4.0/4.1/4.2/5.0 wireless Technology

Technical Specifications – Networking and Communications

Bluetooth ^â Specification	4.0/4.1/4.2/5.0 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetoothâ component shall operate as a Class II Bluetoothâ device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth ^â Software Supported Link Topology	Microsoft Windows Bluetoothâ Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping
	LE Dual Mode LE Link Layer
	LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudgir
	Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy
	LE Privacy 1.2 -Extended Scanner Filter Policies
	LE Data Packet Length Extension FAX Profile (FAX)
	Basic Imaging Profile (BIP)2 Headset Profile (HSP)
	Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Technical Specifications – Audio/Multimedia

High-Definition Audio

Engage One System Audio (Realtek ALC3247-CG)

Туре	Integrated
HD Stereo Codec	High-Definition Audio codec
Internal Speaker Amplifier	4-channel DAC, 4-channel ADC, and an integrated stereo Class-D Speaker Amplifier
Sampling	1kHz input sine wave; Sampling frequency=48kHz; 0dB=1Vrms
Analog Audio	Yes, independent analog sound inputs (multiple streaming)
# of Channels on line-out	2 watts per channel output power Stereo (Left & Right channels)
Internal speaker	Yes
Microphone	Yes, stereo digital microphone input with Realtek proprietary Acoustic Echo Cancellation (AEC), Beam Forming (BF), and Noise Suppression (NS) technology, significantly improving voice quality for PC VoIP applications
Maximum Power Output	2W per channel at 5V power supply
Headphone	yes

Technical Specifications – Integrated Camera

Optional integrated high-speed USB 2.0 compliant webcam 5MP resolution CMOS image sensor. The module integrates a USB 2.0 controller, color-processing engine and high-quality image to provide up to 30fps at 5MP size in high-speed mode.

Note: The Integrated webcam is a windows Hello Camera and IR is supported on 5MP Camera

Category	Specification
Module Key Features	1/5"?, F2.0, 5MP, webcam for OS with build-in UVC driver
	Note: The Integrated webcam is a windows Hello Camera and IR is supported on 5MP Camera
Automatic Image Control	Automatic Exposure Control Automatic White Balance Control Automatic Gain Control
Image Quality Control	Brightness, Contrast, Gamma, Hue, Saturation, Sharpness, Backlight Compensation, Anti-Flicker, White Balance, Image Flip, Night Mode, Digital Zoom, Roll and Exposure Controls.
Resolution Support	4:3 ? 5Mp (2560x1920)
	16:9 ? 5Mp (2560x1440), 1080p (1920x1080)
	720p (1280x720), 640x360
Power Saving Support	Suspend, Hibernation
On Board Component	White LED Indicator x1 IR LED x1
	Performance
Device Name	HP 5MP Camera
Brightness Control	-64~64 (0)
Contrast Control	0~64 (32)
Hue Control	-40~40 (0)
Saturation Control	0~128 (64)
Sharpness Control	0~5 (0)
Gamma Control	72~500 (100)
White Balance	2800~6500, auto (4000, auto)
Backlight	0~1 (0)
Exposure Control	-8~0, auto (-5,Auto)
Low light Compensation	Enable, Disable (Enable)
Anti-flicker (Power line)	50Hz, 60Hz (50Hz)
Format of Image Output Data	YUY2, MJPG

Technical Specifications – Power

POWER

Power Supply	280Watt Smart PFC Standard Barrel 7.4mm Straight 1.8m C14 SR-S; 89% efficiency (advance hub)
	230Watt Smart PFC Slim Barrel 7.4mm Right Angle ; 89% efficiency (Column hub & VESA hub)
Operating Voltage Range	90V~265VAC
Rated Voltage Range	100V~240AC
Rated Line Frequency	50~60HZ
Operating Line Frequency Range	47~63HZ
Rated Input Current	<2.4A RMS/280W, <3.52A/230W
Power Supply Fan	N/A
ENERGY STAR® Compliant	ENERGY STAR [®] certified configurations available and EPEAT [®] registered *
Power Cord Length	1.8m
	NOTE: Power supply meets ENERGY STAR [®] compliance in conjunction with a select range of processors and modules. *Energy Star in under testing & in process of certification at the time this document is written

WEIGHTS & DIMENSIONS

NOTE: Weight and dimensions below do not include MSR, Biometric Reader, Webcam, or CFD.

Head Unit-15.6"			
	Metric	US	
Head Unit-15.6" Dimensions (Landscape)			
Height [mm/in]	26.4	1.0	
Width [mm/in]	397.6	15.7	
Depth [mm/in]	241.0	9.5	
Volume (Litters/cubic inches)	2.5	154.35	
Head Unit-15.6" Dimensions (Portrait)			
Height [mm/in]	26.4	1.0	
Width [mm/in]	397.6	15.7	
Depth [mm/in]	241.0	9.5	
Volume (Litters/cubic inches)	2.5	154.35	
Head Unit-15.6" Weight (Landscape)			
[kg/lb.]	3.37	7.4	
Head Unit-15.6" Weight (Portrait)			
[kg/lb.]	3.35	7.4	

Technical Specifications – Power

Head Unit-19.5"		
	Metric	US
Head Unit-19.5" Dimensions (Landscape)		
Height [mm/in]	29.4	1.2
Width [mm/in]	494.8	19.5
Depth [mm/in]	292.6	11.5
Volume (Litters/cubic inches)	4.3	259.75
Head Unit-19.5" Dimensions (Portrait)		
Height [mm/in]	29.4	1.2
Width [mm/in]	488.8	19.2
Depth [mm/in]	292.6	11.5
Volume (Litters/cubic inches)	4.2	256.60
Head Unit-19.5" Weight (Landscape)		
[kg/lb.]	5.70	12.6
Head Unit-19.5" Weight (Portrait)		
[kg/lb.]	5.69	12.5

Head Unit-23.8"		
	Metric	US
Head Unit-23.8" Dimensions (Landscape)		
Height [mm/in]	29.4	1.2
Width [mm/in]	576.4	22.7
Depth [mm/in]	339.9	13.4
Volume (Litters/cubic inches)	5.8	351.50
Head Unit-23.8" Dimensions (Portrait)		
Height [mm/in]	29.4	1.2
Width [mm/in]	570.4	22.5
Depth [mm/in]	339.9	13.4
Volume (Litters/cubic inches)	5.7	347.84
Head Unit-23.8" Weight (Landscape)		
[kg/lb.]	6.80	15.0
Head Unit-23.8" Weight (Portrait)		
[kg/lb.]	6.79	15.0

Technical Specifications – Power

HP Engage One Pro Advance Hub		
	Metric	US
Hub Dimensions (with U-shape)		
Height [mm/in]	36.8	1.4
Width [mm/in]	305.0	12.0
Depth [mm/in]	220.0	8.7
Hub Dimensions (without U-shape)		
Height [mm/in]	28.5	1.1
Width [mm/in]	275.0	10.8
Depth [mm/in]	100.0	3.9
Hub Weight with U-shape		
Integrated Graphics [kg/lb.]	1.00	2.2
Discrete Graphics [kg/lb.]	1.00	2.2
Hub Weight (without U-shape)		
Integrated Graphics [kg/lb.]	0.69	1.5
Discrete Graphics [kg/lb.]	0.69	1.5

HP Engage One Pro VESA hub		
	Metric	US
Dimensions		
Height [mm/in]	150.0	5.9
Width [mm/in]	125.0	4.9
Depth [mm/in]	24.4	1.0
Weight(Without Adapter)		
[kg/lb.]	547.40	1.20

Technical Specifications – Power

HP Engage One Pro Slim VESA Mount

Metric	US
120.0	4.7
120.0	4.7
10.5	0.4
233.00	0.51
	120.0 120.0

Engage One Pro - Performance Stand only		
	Metric	US
Weight	/	
[kg/lb.]	2.025	4.46

Engage One Pro - Pro Stand only		
	Metric	US
Weight		
[kg/lb.]	0.91	2

Engage One Pro - Vertical Stand on	ıly	
	Metric	US
Weight	, 	
[kg/lb.]	1.33	2.93

System Summary Dimension Matrix

Technical Specifications – Power

Display Heads Only	Width (Horizontal)	Height (Vertical)	Thickness
15.6 Landscape	397.6	241.0	26.4
19.5 Landscape	494.8	292.6	29.4
23.8 Landscape	576.4	339.9	29.4
15.6 Portrait	241.0	391.6	26.4
19.5 Portrait	292.6	488.8	29.4
23.8 Portrait- Slim VESA only*	339.9	570.4	29.4

NOTE: *23.8"? Portrait can only be support with SLIM VESA mount, not configurable with any Column stand, not configurable with column hub

	Width	Depth	Thickness
Stability Base Only	305.0	220.0	11.7
Stability Base With Advance Hub	305.0	220.0	38.7
Delta Height with Advance hub (Note 1 - Add 27 mm to height dimensior when using with the Advance Hub)	305.0	220.0	27.0

Performance Stand Low Position With Stability Base Dimensions		Angle From Vertical orward, Positive =		+120 Tilt Angle From Vertical (Negative - Forward, Positive = Rear)		
	Height Top Edge of Screen (Note 1)	Height Bottom Edge of Screen (Note 1)	Overall Depth	Height Top Edge of Screen (Note 1)	Height Bottom edge of screen (Note 1)	Overall Depth
15.6L	313.5	112.1	220.0	289.8	146.6	220.0
19.5L	335.2	92.3	234.8	305.3	133.7	256.8
23.8L	353.3	74.2	250.0	317.1	121.8	251.6
15.6P	371.1	54.4	264.4	327.4	108.9	274.0
19.5P	410.3	17.1	297.9	354.3	84.6	437.9
23.8P VESA only	NA	NA	NA	NA	NA	NA

NOTE: *23.8"? Portrait can only be support with SLIM VESA mount, not configurable with any Column stand, not configurable with column hub

Add 27 mm to all height dimensions if unit has Advance hub attached to the Column Stand

Technical Specifications – Power

Performance Stand High Position With Stability Base	+40 Tilt Angle From Vertical Forward Travel Limit (Negative - Forward, Positive = Rear)				Angle From Vertica orward, Positive =	
Dimensions	Height Top Edge of Screen (Note 1)	Height Bottom Edge of Screen (Note 1)	Overall Depth	Height Top Edge of Screen (Note 1)	Height Bottom edge of screen (Note 1)	Overall Depth
15.6L	363.5	162.1	220.0	339.8	196.6	220.0
19.5L	385.2	142.3	234.8	355.3	183.7	256.8
23.8L	403.3	124.2	250.0	367.1	171.8	251.6
15.6P	421.1	104.4	264.4	377.4	158.9	274.0
19.5P	460.3	67.1	297.9	404.3	134.6	437.9
23.8P VESA only	NA	NA	NA	NA	NA	NA

NOTE: *23.8"? Portrait can only be support with SLIM VESA mount, not configurable with any Column stand, not configurable with column hub

Add 27 mm to all height dimensions if unit has Advance hub attached to the Column Stand

HP Engage Pro Stand With Stability Base Dimensions	+40 Tilt Angle From Vertical (Negative - Forward, Positive = Rear)			+120 Tilt Angle From Vertical (Negative - Forward, Positive = Rear)		
	Height Top Edge of Screen (Note 1)	Height Bottom Edge of Screen (Note 1)	Overall Depth	Height Top Edge of Screen (Note 1)	Height Bottom edge of screen (Note 1)	Overall Depth
15.6L	313.4	112.0	224.0	289.6	146.4	232.9
19.5L	335.0	92.2	234.8	305.1	135.5	267.9
23.8L	380.2	101.1	240.8	317.0	121.7	308.9
15.6P	371.0	54.3	271.1	327.3	108.8	352.1
19.5P	410.2	17.0	336.6	354.2	84.5	437.9
23.8P VESA only	NA	NA	NA	NA	NA	NA

NOTE: *23.8"? Portrait can only be support with SLIM VESA mount, not configurable with any Column stand, not configurable with column hub

Add 27 mm to all height dimensions if unit has Advance hub attached to the Column Stand

HP Engage Vertical Stand With Stability Base Dimensions		Angle From Vertica orward, Positive =		+40 Tilt Angle From Vertical (Negative - Forward, Positive = Rear)		
	Height Top Edge of Screen (Note 1)	Height Bottom Edge of Screen (Note 1)	Overall Depth	Height Top Edge of Screen (Note 1)	Height Bottom edge of screen (Note 1)	Overall Depth
15.6L	339.9	100.4	220.0	316.9	115.5	220.0
19.5L	316.9	115.5	220.0	365.7	75.5	230.2
23.8L	388.5	52.6	220.0	356.8	77.7	245.4
15.6P	412.7	27.7	221.4	374.6	57.9	259.7
19.5P	NA	NA	NA	NA	NA	NA
23.8P VESA only	NA	NA	NA	NA	NA	NA

NOTE: *23.8"? Portrait can only be support with SLIM VESA mount, not configurable with any Column stand, not configurable with column hub

Add 27 mm to all height dimensions if unit has Advance hub attached to the Column Stand

Technical Specifications - Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
- Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or poweredoff state without affecting other elements of the system.
- Intel[®] Wired for Management support; industry wide initiative to make Intel[®] architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

HP Point of Sale Diagnostics UEFI:

• This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support

Serviceability Features:

- System/Emergency ROM
- Flash ROM
- Flash Recovery with Video Configuration Record Software
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- Clear CMOS Button
- Color coordinated cables and connectors
- Front power switch
- System memory can be upgraded without removing the system board or any internal components

Interpreting System Validation Diagnostic Front Panel LEDs and Audible Codes

During the system validation phase that occurs at system startup, the BIOS validates the functionality of the following subsystems and conditions:

- AC adapter
- System board power
- Processor failure
- BIOS corruption
- Memory failure
- Graphics failure
- System board failure
- BIOS authentication failure

If an error is detected, specific patterns of long and short blinks, accompanied by long and short beeps (where applicable) are used to identify the error. These patterns will make up a two part code:

- Major the category of the error
- Minor the specific error within the category

Single beep/blink codes are not used.

89 A

Technical Specifications - Miscellaneous Features

Error category
Not used
BIOS
Hardware
Thermal
System board

Patterns of blink/beep codes are determined by using the following parameters:

- 1 second pause occurs after the last major blink.
- 2 second pause occurs after the last minor blink.
- Beep error code sequences occur for the first 5 iterations of the pattern and then stop.
- Blink error code sequences continue until the computer is unplugged or the power button is pressed.

NOTE: Not all diagnostic lights and audible codes are available on all models.

The red LED blinks to represent the major error category (long blinks). The white LED blinks to represent the minor error category (short blinks). For example, '3.5' indicates 3 long red blinks and 5 short white blinks to communicate the processor is not detected.

Category	Major/minor code	Description
BIOS	2.2	The main area (DXE) of BIOS has become corrupted and there is no recovery binary image available.
	2.3	The embedded controller policy requires the user to enter a key sequence
	2.4	The embedded controller is checking or recovering the boot block.
Hardware	3.2	The embedded controller has timed out waiting for BIOS to return from memory initialization.
	3.3	The embedded controller has timed out waiting for BIOS to return from graphics initialization.
	3.4	The system board displays a power failure (crowbar).*
	3.5	The processor is not detected.*
	3.6	The processor does not support an enabled feature.
Thermal	4.2	A processor over temperature condition has been detected.*
	4.3	An ambient temperature over temperature condition has been detected.
	4.4	An MXM over temperature condition has been detected.
System board	5.2	The embedded controller cannot find valid firmware.
	5.3	The embedded controller has timed out waiting for the BIOS.
	5.4	The embedded controller has timed out waiting for BIOS to return from system board initialization.
	5.5	The embedded controller rebooted the system after a possible lockup condition had been detected through the use of a System Health Timer, Automated System Recovery Timer, or other mechanism.

Technical Specifications - Miscellaneous Features

TEMPERATURE, HUMIDITY, ALTITUDE

Temperature	Operating	50° to 104° F (10 to 40° C)
	Non-operating	-22° to 149° F (-30°to 65° C)
Humidity	Operating	20%-85% relative humidity at max inlet temperature
	Non Operating	20%-85% relative humidity at max inlet temperature
Shock	Operating	40g, six surfaces
	Non Operating	30g, six surfaces
Vibration	Operating	2-g peak acceleration
	Non Operating	3-g peak acceleration
Altitude	Operating	0 to 10,000 ft (3,048 m)
(unpressurized)	Non-operating	0 to 30,000 ft (9,144 m)

Technical Specifications - Environmental

ENVIRONMENTAL & INDUSTRY

Environmental Data

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:
	 IT ECO declaration US ENERGY STAR® certified configurations available EPEAT® Silver registered configurations available in the United States. See http://www.epeat.net for registration status in your country.
Sustainable Impact Specifications	 54% post-consumer recycled plastic⁴ Low halogen¹ Ocean-Bound Plastic in speaker enclosure² 25% ITE-derived closed loop plastic⁶
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Engage One Pro model is based on a typically configured system featuring an SSD, a high efficiency power supply, and a Microsoft Windows® operating system.

HP Engage One Pro AiO System Model 15.6"?

115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
12.58W	13.07W	12.65 W
10.71 W	10.96W	10.79 W
3.28 W	3.31W	3.26 W
1.15W	1.18 W	1.15 W
115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
42.89 BTU/hr	44.59 BTU/hr	43.02 BTU/hr
36.54 BTU/hr	37.39 BTU/hr	36.74 BTU/hr
11.15 BTU/hr	11.29 BTU/hr	11.12 BTU/hr
3.92 BTU/hr	3.99 BTU/hr	3.92 BTU/hr
	12.58W 10.71 W 3.28 W 1.15W 115VAC, 60Hz 42.89 BTU/hr 36.54 BTU/hr 11.15 BTU/hr	12.58W 13.07W 10.71 W 10.96W 3.28 W 3.31W 1.15W 1.18 W 115VAC, 60Hz 230VAC, 50Hz 42.89 BTU/hr 44.59 BTU/hr 36.54 BTU/hr 37.39 BTU/hr 11.15 BTU/hr 11.29 BTU/hr

* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour

	Idle Operati		ng Idle		Operating	
	ECMA-74 C.15.3.2 Idle mode	ECMA-74 C.9.3.2 Drive Random Seek	ECMA-74 C.15.3.3 g Active Mode	ECMA-74 C.15.3.2 Idle Mode	ECMA-74 C.9.3.2 Drive Random Seek	ECMA-74 C. 15.3.3 g Active Mode
Landscape	2.7	2.8	3.6	17.8	18.8	26.5
Portrait	2.7	2.7	3.5	17.6	18.5	24.3

NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

HP Engage One Pro AiO System Model 19.5"?

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured - Idle Fixed Disk - Random writes

Technical Specifications - Environmental

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	12.58W	13.07W	12.65 W
Normal Operation (Long idle)	10.71 W	10.96W	10.79 W
Sleep	3.28 W	3.31W	3.26W
Off	1.15W	1.18 W	1.15 W
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	42.89 BTU/hr	44.59 BTU/hr	43.02 BTU/hr
Normal Operation (Long idle)	36.54 BTU/hr	37.39 BTU/hr	36.74 BTU/hr
Sleep	11.15 BTU/hr	11.29 BTU/hr	11.12 BTU/hr
Off	3.92 BTU/hr	3.99 BTU/hr	3.92 BTU/hr

* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour Operating Idle Idle Onerating

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Ture	operating		aperuarig fale		Ture	- P	raang
ECMA-74 C 15.3.2 Idle mode Seek	ECMA-74 C.15.3.3 g Active Mode	ECMA-74 C.15.3.2 Idle Mode	ECMA-74 C.9.3.2 Drive Random Seek	ECMA-74 C.15.3.3 (Active Mode				
Landscape	2.7	3.2	3.5	18.7	19.5	25.6		
Portrait	2.9	3.3	3.6	19.1	21.1	26.1		

Typically Configured - Idle Fixed Disk - Random writes

HP Engage One Pro AiO System Model 23.8"?

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	12.58W	13.07W	12.65 W
Normal Operation (Long idle)	10.71 W	10.96W	10.79 W
Sleep	3.28 W	3.31W	3.26W
Off	1.15W	1.18 W	1.15 W
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	42.89 BTU/hr	44.59 BTU/hr	43.02 BTU/hr
Normal Operation (Long idle)	36.54 BTU/hr	37.39 BTU/hr	36.74 BTU/hr
Sleep	11.15 BTU/hr	11.29 BTU/hr	11.12 BTU/hr
Off	3.92 BTU/hr	3.99 BTU/hr	3.92 BTU/hr

* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour

Declared Noise Emissions	20 - S. L.	Idle	Operat	ing	Idle	Oper	ating
(in accordance with ISO 7779 and ISO 9296)		ECMA-74 C.15.3.2 Idle mode	ECMA-74 C.9.3.2 Drive Random Seek	ECMA-74 C.15.3.3 g Active Mode	ECMA-74 C.15.3.2 Idle Mode	ECMA-74 C.9.3.2 Drive Random Seek	ECMA-74 C.15.3.3 g Active Mode
Turically Configured Idle	Landscape	3.0	3.0	3.5	18.6	19.5	25.7
Typically Configured – Idle	Portrait	3.1	3.1	3.5	19.3	21.2	27.6

Fixed Disk - Random writes

Technical Specifications - Environmental

Longevity and Upgrading		an be upgraded, possibly extending its useful life by seve or components contained in the product may include:	eral years. Upgradeable
	 M.2 22 (1) M.2 	nory slots 230 slot for WLAN 2 2280 slot for SSD re available throughout the warranty period and or for up	p to "5"? years after the end of
Batteries	Batteries use Mercury g Cadmium	a) in this product comply with EU Directive 2006/66/EC d in the product do not contain: greater the1ppm by weight greater than 20ppm by weight ER2032 (coin cell) Lithium	
Additional Information	Substa This F Electro This p Califor This p the <s Plastic ISO11 This p</s 	roduct is in compliance with the Restrictions of H ances (RoHS) directive - 2011/65/EC. IP product is designed to comply with the Waste onic Equipment (WEEE) Directive - 2002/96/EC roduct is in compliance with California Proposition roduct is in compliance with California Proposition roduct is in compliance with the IEEE 1680.1 (El Silver> level, see www.epeat.net cs parts weighing over 25 grams used in the pro- 469 and ISO1043. roduct contains 45.16% post-consumer recycled roduct is 96% recycle-able when properly disposed	e Electrical and 5. on 65 (State of nt Act of 1986). PEAT) standard at duct are marked per d plastic (by wt.)
Packaging Materials	External:	PAPER/Corrugated	TBD
	Internal:	PLASTIC/Polyethylene Expanded - EPE	TBD
		PLASTIC/Polyethylene low density - LDPE	TBD
	The EPE foar	n packaging material is made from 100% recycled conten	ıt.
	The corrugat	ed paper packaging materials contains at least 35% recy	cled content.
Material Usage	to the HP Gen	loes not contain any of the following substances in exces eral Specification for the Environment at p.com/hpinfo/globalcitizenship/environment/pdf/gse.pc	
	 Certai retard. Cadm Chlorin Chlorin Forma Halogo Lead a Lead a Mercut Nickel freque Ozone 	n Azo Colorants n Brominated Flame Retardants - may not be us ants in plastics ium nated Hydrocarbons nated Paraffins	

Technical Specifications - Environmental

	 Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) - except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances <u>Tributyl Tin-(TBT), Triphenyl Tin-(TPT), Tributyl Tin Oxide-(TBTO)</u> Notes: * EPE foam packaging material is considered "recycled"? pre-Consumer. The scrap or waste EPE material from the manufacturing process of these EPE foam pieces are re-introduced into the manufacturing process.
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	 HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest H sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP Inc. web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP Inc. Corporate Environmental Information	For more information about HP's commitment to the environment Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: PC Product Design ISO 14001 certificate and HP Operations ISO 14001 certificate
Footnotes	¹ External power supplies, WWAN modules, power cords, cables and peripherals excluded. Service parts obtained after purchase may not be Low Halogen.
	² Percentage of ocean-bound plastic contained in each component varies by product
	⁴ Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.

Technical Specifications - Environmental

⁶ITE Derived Closed Loop Plastic percentage is based on the definition set in the IEEE 1680.1-2018 standard.

HP Engage One After Market Option Matrix

HP Engage One Pro Advance Hubs & cable AMOs

AMO Part No.	Description
9YH40AA#xxx 156N6AA#xxx	HP Engage One Pro Adv Fan-less Hub * HP Engage One Pro Adv Fan-less Hub White *
*Included 280W PSU/1.8M cord, need one of the separate cable I	
2Z8M9AA 2Z8N0AA 2Z8N2AA 2Z8N1AA	HP Engage One Pro 2m USB-C® cable black HP Engage One Pro 0.5m USB-C® cable black HP Engage One Pro 2m USB-C® cable gray HP Engage One Pro 0.5m USB-C® cable gray
	140 W USB power cord*

Additional Cable available to connect the Column hub or the VESA hub to the Advance hub below

201A2AA	HP Engage One Pro Column/VESA hub to Advance hub 2m black
201A1AA	HP Engage One Pro Column/VESA hub to Advance hub 0.5m black
316D6AA	HP Engage One Pro Column/VESA hub to Ad hub 2m gray
316D7AA	HP Engage One Pro Column/VESA hub to Ad hub 0.5m gray

HP Engage One Pro VESA Hubs & cable AMOs

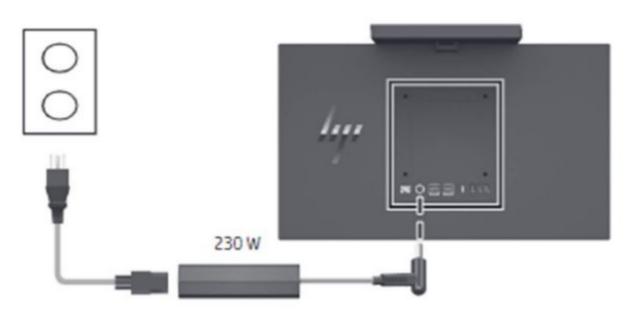
HP Engage One After Market Option Matrix

9YH42AA#xxx

**Included 230W PSU/1.8M cord & cable

Description

Engage One Pro VESA Hub**



Additional Cable available to connect the Column hub or the VESA hub to the Advance hub below

201A2AA	HP Engage One Pro Column/VESA hub to Advance hub 2m black
201A1AA	HP Engage One Pro Column/VESA hub to Advance hub 0.5m black
316D6AA	HP Engage One Pro Column/VESA hub to Ad hub 2m gray
316D7AA	HP Engage One Pro Column/VESA hub to Ad hub 0.5m gray

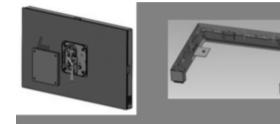
HP Engage One Pro Mounting Option AMOs

HP Engage One After Market Option Matrix

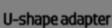
AMO Part No.

1A4E7AA	Engage One Pro Slim VESA
326R7AA	Engage One Pro Slim VESA White
9YH43AA	Engage One Pro U-shaped Adapter
156N7AA	Engage One Pro U-shaped Adapter White
1A4E5AA	HP Engage One Pro AiO Stability Plate
1A4E6AA	HP Engage One Pro AiO Stability Plate White
2W7M4AA	Engage One Pro Flexible Pole Single Mount
2W7M3AA	Engage One Pro Flexible Back-to-Back Bracket
9YH51AA	Engage One Pro Undercounter Mount

Description



Slim VESA w/head unit

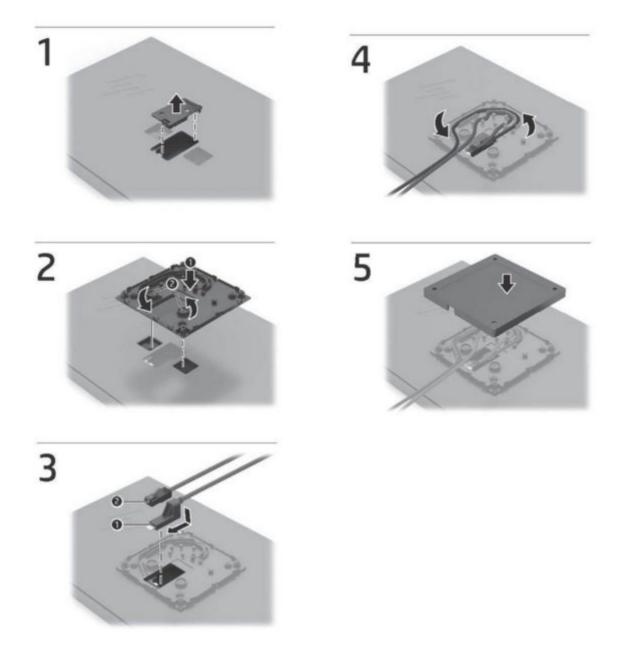


Stability Plate

Ð

Counter Mount

HP Engage One After Market Option Matrix



HP Engage One Pro Mounting Option AMOs

HP Engage One After Market Option Matrix

AMO Part No.

2W7M4AA

2W7M3AA

<image>

Description

Engage One Pro Flexible Pole Single Mount

Engage One Pro Flexible Back-to-Back Bracket

HP Engage One Pro Customer Facing Displays (CFDs)

HP Engage One After Market Option Matrix

AMO#	Description
9YH48AA	HP Engage One Pro 6.6 inch Customer Facing Display
156N8AA	HP Engage One Pro 6.6 inch White Customer Facing Display
10P79AA	HP Engage 6.6 inch Pole Display
156N9AA	HP Engage 6.6 inch W Pole Display
1XD80AA#ABA, #ABT, #AC3	HP Engage One 10 Display
1XD81AA#ABA, #ABT, #AC3	HP Engage One 10t Display
3FH66AA#ABA, #ABT, #AC3	HP Engage One 10w Display
3FH67AA#ABA, #ABT, #AC3	HP Engage One 10tw Display
20C49AA#AB1, #AB2, #ABT, #AC3	HP Engage One 14 FHD Monitor
20C50AA#AB1, #AB2, #ABT, #AC3	HP Engage One 14 FHD No Stand Monitor
20C51AA#AB1, #AB2, #ABT, #AC3	HP Engage One 14t FHD Monitor
20C52AA#AB1, #AB2, #ABT, #AC3	HP Engage One 14t FHD No Stand Monitor
2D9V5AA#ABT, #AC3	HP Engage One 16t FHD Monitor
2D9X0AA#ABT, #AC3	HP Engage One 16t FHD No Stand Monitor
2D9Y5AA#ABT, #AC3	HP Engage One 16ts FHD Monitor
2D9Z4AA#ABT, #AC3	HP Engage One 16ts FHD No Stand Monitor

HP Engage One Pro Customer Facing Displays (CFDs) Stands

AMO#	Description
10P60AA	HP Engage 6 Clean Mount Arm Bracket
10P61AA	HP Engage 6 Stability Mount Arm Bracket
10P77AA	HP Engage 10 Clean Mount Stand
10P78AA	HP Engage 10 Stability Mount Stand
10P58AA	HP Engage 14 Clean Mount Stand
10P62AA	HP Engage 14 Stability Mount Stand

HP Integrated Peripherals AMOs

AMO#	Description
9YH50AA	HP Engage One Pro Fingerprint Reader
2U551AA	HP Engage One Pro Magnetic Stripe Reader
2V9G4AA	HP Engage One Pro White Magnetic Stripe Reader
9YH49AA#AB4, #ABA, #ABB	HP Engage One Pro Bar Code Scanner

Overview - After Market Options

HP Engage 6.6 inch Customer Facing Display

Model

HP Engage 6.6 inch Customer Facing Display HP Engage 6.6 inch Customer Facing Display White

Introduction

Give customers a clear view of their transactions and sharing engaging, colorful, dynamic content at the point of sale with LCD touch

Key Benefits

- 6.6 inch diagonal compact LCD display that integrates easily into your retail solution.
- Position as need with adjustable height and swiveling of the display head.
- Place the durable, dust resistant display in a range of high traffic areas.
- A USB connector powers the display and eliminated the need for additional cabling.
- The edge to edge, bezel free desing is easy to clean, helps protection from dust, and create a sleek, moder appearance.

Compatibility

The HP Engage 6.6 inch Customer Facing Display is compatible with HP Retail Point of Sale Systems.

Note: Not all Point of Sale system models are available in all regions.

Service and Support

Three (3) year limited warranty with advance exchange when purchased from HP.

Overview - After Market Options

General
ueneral

Kit Cont	tents	
	compatible with.	Windows To Professional d4-bit) Windows 10 IoT Enterprise 2019 LTSC (64-bit) Windows Server 2019 Standard FreeDos 3.0 Ubuntu Desktop 18.04 LTS CentOS 7 Android 11
υμειαί	Compatible with:	Windows 10 Professional 64-bit)
Onerati	ng System	Note: The Integrated webcam is a windows Hello Camera and IR is supported on 5MP Camera
	Webcam	30fps USB 2.0 webcam, 5MP (2560x1920) resolution
	Non-operating	-30°C to 65°C [-22 to 149°F] at 0% to 95% humidity (38.7°C maximum wet bulb temperature)
	Operating	0°C to 35°C [32 to 95°F] at 10% to 90% humidity (non-condensing)
Temper	ature Range	
	Idle Current 0.64W	TBD
	Full Load Current	6.5W (DC +5V, 1300mA)
	Operating Voltage	5V
Power	Interface	
connect	lion Interface	USB
Connect	Color	HP Black / White
		Folded to 90° for shipping
	Hinge Adjustability	0.25 kg Rotation Range 0°~90° (normal using)
	(WxHxD) Display Weight	0.25 kg
	Display Dimensions	171.4 x 76.2 x 56.35 mm
Mechan	ical	
	Color Gamut	70% (CIE 1931 Standard NTSC)
	Viewing Angle	Left: 85° Right: 85° Top: 85° Bottom: 85°
	Response Rate	25 ms (rise+fall time)
	Contrast Ratio	1000:1 (max)
	Active Area	75.6 (H) x 151.2 (V) mm
	Pixel Pitch	0.105 x 0.105 mm
	Resolution	1440 x 720
	Brightness	400 Nits
	Display Method	Backlit LED

HP Engage 6.6 inch Customer Facing Display, documentation, warranty card.

Overview - After Market Options

HP Engage One Pro Bar Code Scanner*

*Integrated scanner supports OCR Passport Reading

Model

HP Engage One Pro Bar Code Scanner (Americas)	9YH4
HP Engage One Pro Bar Code Scanner (Europe)	9YH4
HP Engage One Pro Bar Code Scanner (Asia)	9YH4

Compatibility

The HP Engage One Pro Barcode Scanner is compatible with the HP Engage One Pro All-in-One system.

Service and Support

Three (3) year limited warranty with advance exchange when purchased from HP.

General

Image Sensor	1200 x 800 CMOS	
Illumination Aimer	White LED Red LED 625± 10nm	
Depth of Field	Typical Performance * Narrow Width Code 39 Data Matrix EAN-13 PDF-417 QR Code	Depth of Field 5 mils:90 to 215mm 10 mils: 65 to 180mm 13 mils: 70 to 190mm 6.7 mils: 70 to 190mm 15 mils: 40 to 245mm
Symbol Contrast	25% minimum reflectance	
Roll (tilt)	360°	
Pitch	±60°	
Skew	±60°	
Field of View	Horizontal 42°, Vertical 28	°
1D decode symbologies	Autodiscriminates all st	andard 1D codes including GS1 DataBar™ linear codes.
2D decode symbologies	Aztec Code Chinese Sensible Code Code One Data Matrix GM Code MaxiCode MicroPDF417 Micro QR Code PDF417 QR Code	

Overview - After Market Options

	Postal decode	Australian Post
	symbologies	KIX Post
		Royal Mail USPS Planet
		USPS Postnet
	OCR symbologies	Passport OCR
Mechani	cal	
	Dimensions (W xD x H)	30.4 x 45.8 x 9.8 mm
	Weight	15g
	Color	Black
Interface	e/Connection	
	Interface	USB
Tempera	ture	
	Operating	-20°C to 50°C (-4°F to 140°F)
	Storage	-40°C to 70°F (-40°F to 158°F)
	Humidity (non-condensing)	5% to 95%
Power		
	Operating Voltage	5VDC±5%
	Current at 5VDC	Operating: 500~700mA (RMS typical), 800mA (RMS max.)
		Idle: <70mA
		Sleep: <1mA
		3W
Drivers		
	Windows USB HID-KB and OP	OS & JPOS (via USB-COM mode drivers)
Ambient	Light	0- 100,000 lux
Water Pe	enetration Protection	IP54
Operatin	g System	
	Compatible with:	Windows
		Windows 10 Pro 64bit
		Windows 10 IoT Enterprise 2016 LTSB 64bit (RS1) Windows 10 IoT Enterprise 2019 LTSC 64bit (RS5)
		Linux
		Red Hat/CentOS 5.6.8and above (64 bit)
		Suse Linux Enterprise 11/12 SP3 and above (64 bit) Ubuntu 12.04/14.04 LTS and above (64 bit)
		Android
_		Android 8-0 and above
Agency (Certifications	
FCC Part15, Class B, CE EMC Class B, IEC62471, RoHS, IEC 62368-1		
Kit Conte	ents	

HP Engage One Pro Barcode Scanner, documentation, warranty card.

Overview - After Market Options

HP Engage One Magnetic Stripe Reader

Model

HP Engage One Pro Magnetic Stripe Reader HP Engage One Pro White Magnetic Stripe Reader

Compatibility

The HP Engage One Pro Magnetic Stripe Reader is compatible with the HP Engage One Pro All-in-One System.

NOTE: Not all Point of Sale system models are available in all regions.

Service and Support

Three (3) year limited warranty with advance exchange when purchased from HP.

General

	Magnetic stripe formats	ISO 7811, AAMVA
	Card Thickness	0.38 to 1.14 mm (0.015 to 0.045 in)
	Indicators	Bi-colored LED, beeper (requires system audio driver)
	Card Speed	3 to 75 ips (7.6 to 190.5 cm/s)
Mechanic	al	
	Weight	5.67 g
	Slot width	1.14 mm (0.045 in)
	Color	HP Black HP White
Connectio	on	
	Interface	Eight-pin male Molex 51021-0800
	Cable Length	125 ± 6.4 mm
Power		
	Power Supply	3.0 to 3.6 VDC
	I/O Voltage Range	2.7 to 3.6 VDC
	Active Power Supply Current	5
	mA Standby Power Supply Current	0.03 mA
Temperat	ture Range	
	Operating	0°C to 55°C
	Relative Humidity	-10% to 90% non-condensing

Overview - After Market Options

Reliability

Operating Life

1,000,000 card swipes minimum

Agency Certifications

FCC, CE, USB-IF

Operating Systems

Compatible with:

Windows 10 Professional (64-bit) Windows 10 IoT Enterprise 2019 LTSC (64-bit) Windows 10 IoT Enterprise 202x LTSC (64-bit) Windows Server 2016 Standard Windows Server 2019 Standard FreeDos 3.0 Ubuntu Desktop 18.04 LTS CentOS 7 Android 11

Kit Contents

HP Engage One Pro Magnetic Stripe Reader, documentation, warranty card.

HP Engage One Pro Fingerprint Reader

Model

HP Engage One Pro Fingerprint Reader

Compatibility

The HP Engage One Pro Fingerprint Reader is compatible with the HP Engage One Pro All-in-One System.

Service and Support

Three (3) year limited warranty with advance exchange when purchased from HP.

Overview - After Market Options

General	·	
	Sensor Type	Capacitive
	Array Size	208 x 288 pixels
	Image Resolution	508 DPI
	Gray Scale	8-bit (256 levels)
Mechani	cal	
	Image Area	10.4 x 14.4 mm
	Junage/Coating	Steel Coat
	Color	HP Black
Digital ID) Reliability	
	NVM Storage	100 templates
	Data Retention	20 years
	Erase/Write	100,000 cycles
Interfac	e/Connection	
	Interface	USB 2.0
	Interface Connector	5 pin, 0.8mm pitch wire-type (gold-plated)
Tempera	iture	
	Operating	-30° to +85°C
	Storage	-40° to +85°C
	Humidity (non-condensing)	5% to 85%
	ESD Tolerance	IEC 61000-4-2 Level 4
Power		
	Consumption	Supply voltage: single supply voltage, 3.0V to 3.6V Imaging mode: 105 mA @ 3.3V Sleep mode: 1350 uA @ 3.3V
	Wake-up Time	< 15 ms (Sleep to imaging)
Drivers		
	Windows USB HID-KB and O	POS & JPOS (via USB-COM mode drivers)
Operatin	ig Systems	
	Compatible with:	Windows 10 Professional (64-bit) Windows 10 IoT Enterprise 2019 LTSC (64-bit) Windows 10 IoT Enterprise 202x LTSC (64-bit) Windows Server 2016 Standard Windows Server 2019 Standard FreeDos 3.0 Ubuntu Desktop 18.04 LTS CentOS 7 Android 11
Agency (Certifications	
	FCC (47 CFR) Part 15C, Secti	ion 15.247 & 15.249
Kit Conto		
	HP Engage One Pro Fingerpr	int Reader, documentation, warranty card.

Overview - After Market Options

HP Engage One Serial USB Thermal Printer

Model

HP Engage One Serial USB Thermal Printer (Black) HP Engage One Serial USB Thermal Printer (White)

Introduction

Redefine your perception of retail printing with the HP Engage One Serial USB Thermal Printer, an eye-catching, compact, cubist print dazzle alongside your HP Engage One AiO System at the point of sale.

Key Features and Benefits

- Print quickly with 114 mm per second print speed and 8 MB of integrated memory. Add your logo, special of or coupons to receipts with 203 DPI and fonts that include Unicode, Arabic, and Asian.
- Connect to your retail system with an optional USB, PUSB or Serial cable kit (sold separately), and drive up two optional cash drawers through connections on the printer.
- Place the ultra-compact printer where you need it with the assurance that the internal steel frame can withs the everyday wear and tear of retail environments.

Compatibility

The HP Engage One Serial USB Thermal Printer is compatible with the HP Engage One AiO Systems.

NOTE: Not all Point of Sale system models are available in all regions. Not all HP Cash Drawer models are available in all regions. This printer does not comply with fiscalization requirements that may be required in certain countries.

Service and Support

Three (3) year limited warranty with advance exchange when purchased from HP.

General

Supported Character Sets Resident Code Pages:

437 (US) 720(Arabic) 737(Greek) 775(Lithuanian) 850(Multilingual) 852 (Slavic)

Overview - After Market Options

	Bar Codes	857(Turkish) 858 (with Eurosymbol) 860(Portuguese) 862(Hebrew) 863(French Canadian) 864(Arabic) 865(Nordic) 866(Cyrillic) 874 (Thai) 932(Kanji) 936(Simplified Chinese) 949(Korean - Hangul) 950(Traditional Chinese) KZ_1048 (Kazakh) 1250(Latin) 1251(Cyrillic) 1252(Windows Latin I) 1254(Turkish) 1255(Hebrew) 1256(Arabic) 1257(Baltic) Katakana 28591 (IS08859-1, Latin 1) 28594 (IS08859-4, Latin 4) 28594 (IS08859-4, Latin 4) 28599 (IS08859-5, Latin 5/Turkish) 28605 (IS08859-15, Latin 9) Unicode UTF-8 encoding for listed code pages 10: UPC-A, UPC-E, EAN8, EAN13, Code 39, Code 93, Interleaved 2 of 5
		Codabar, Code 128, Code 128,EAN 128, GS1 Databar 2D: Datamatrix, QR code, PDF 417
	Print Method	Direct Thermal
	Printing Speed	114 mm/sec (33.75 LPS)
	Printer Sensor	Low: No
		Out: Yes
	Resolution	203 DPI
	Flash Memory	8 MB
	RAM	8 MB
	Knife	Full and Partial cuts supported
	Receipt-Columns	44/56
	Paper Type	Direct Thermal Monochrome POS Grade(s)
	Paper Roll Size (W x D)	3.1 in. X 3.26 in. (80 mm X 83 mm)
	Paper Thickness Range	2.3 - 3.2 mil
	Cash Drawers	1 connector can drive 2 cash drawers with separately purchased splitter cable (default configuration is connection to 1 cash drawer)
Mechan	ical	
	Dimensions (WxDxH)	4.4 in. X 5.2 in. X 4.06 in. (111.8 mm X 131.6 mm X 103 mm)
	Weight	1.75lbs. (.793 kg) (printer only)
	Color	Ebony Black or Ceramic White

Overview - After Market Options

Interface/Connection

Interface/Connection	
Interface	RS232 (9-Pin Female to 9-Pin Female NULL modem cable) or standard USB 2.0 cable. 24V Cash Drawers support with RJ 12 interface
Power	
External Power Supply	48 w
Operating Voltage	24 V
Full Load Current	2 A w/active power management system
Idle Current	25mA
Idle Power	0.6 W
Temperature Range	
Operating	41°F to 95°F (5°C to 35°C) at 5% to 90% humidity 95°F to 122°F (35°C to 50°C) at 5% to 40% humidity
Non-operating	Transit range: -40°F to 140°F (-40°C to 60°C) 5% to 95% humidity Storage range: 14°F to 122°F (35°C to 50°C) at 5% to 90% humidity
Drivers	
Windows, OPOS, JPOS	
Operating System	
Compatible with:	Windows
	 Windows 10 IoT Enterprise for Retail (64-bit) Windows 10 Pro (64-bit) Linux Pod Hot/ContOS 6 and 7 (22 bit and 64 bit)
	 Red Hat/CentOS 6 and 7 (32-bit and 64 bit) Suse Linux® Enterprise POS 11 and 12 (32-bit and 64-bit) Ubuntu 14.04 LTS (32-bit and 64-bit) Android 11
Reliability	
MCBF Print Mechanism: MCBF Knife Cuts: 1-milli Print Head Life: 100 km	on
Agency Certifications	
Flammability:	UL 94V-0
Safety:	UL 60950-1 2nd edition 2014-10-14; UL 62382-1 CAN/CSA C22.2 No. 60950-1-07, 2nd Edition, 2014-10 EN 60950-1:2006 + A1:2010+ A2:2013 IEC/EN 62382-1 2ND Edition CB Report: IEC 60950-1:2005 + A1:2009 +A2:2013 GB4943.1-2011-China IS 13252-1 (2010)/A1:2013/A2:2015
Radiated Emissions:	FCC 47CFR, Part 15, Class B ICES-003: 2012, Issue 6, Class B EN 55032:2015 Class B CISPR22 Class B VCCI: V-3/2015.04 Class B AS/NZS 3548
Immunity:	EN55024: 2010 EN61000-4-2 Level 4 (8kV direct, 15kV air discharge) EN61000-4-3: Level 3 (10V/m) EN61000-4-6 Level 3 (10V rms)

EN61000-4-6 Level 3 (10V rms)

RoHS, WEEE

EN61000-4-4: Level 3 (2kV mains, 1kV data lines)

Overview - After Market Options

Kit contents

HP Engage One Serial USB Thermal Printer, starter paper roll **NOTE:** This printer does not comply with fiscalization requirements that may be required in certain countries. Cable kits sold separately: 1RM02AA - HP Engage One USB + Pwr Adapter 1RM03AA - HP Engage One Serial + Pwr Adapter BM477AA - HP PUSB Y Cable 1RM05AA - HP Engage One PUSB Pw only 3WV53AA - HP Engage One W Printer USB + Pwr Adpter 3WV54AA - HP Engage One W Printer Serial + Pwr Adptr 3WV55AA - HP Engage One W Printer PUSB Y Cable 5FW23AA - HP Engage One W Printer Serial + PUSB Pw only

NOTE: For cable routing configuration information refer to HP Engage One AiO System quick specs.

Service and Support

Ninety-day (90-90-90), one-year (1-1-1), and three-year (3-3-3) limited warranty delivers (ninety days/one year/three years) of on-s business day² service for parts and labor and complimentary limited technical support.³ Three-year onsite and labor are not available countries. Service offers terms up to 5 years by choosing an optional HP Care Pack.¹ To choose the right level of service for your HP | HP Care Pack Central: http://http://www.hp.com/go/cpc

NOTES:

- 1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in yc
 - 2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is r certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
 - 3. Technical support applies only to HP-configured Compaq and third-party HP-qualified hardware and software. 24 x 7 support r available in some countries.

Summary of Changes

Date of change:	Version History:		Description of change:
March 2, 2021	From v1 to v2	Changed	At A Glance and ENVIRONMENTAL & INDUSTRY sections
April 14, 2021	From v2 to v3	Changed	Environmental Data section
April 28, 2021	From v3 to v4	Changed	Networking and HP Engage One Pro Advance Hubs & cable AMOs sections
May 3, 2021	From v4 to v5	Changed	Ports section
May 28, 2021	From v5 to v6	Changed	HP Engage 6.6 inch Customer Facing Display section
May 31, 2021	From v6 to v7	Changed	HP Smart Support and footnote
June 9, 2021	From v7 to v8	Changed	WEIGHTS & DIMENSIONS section
June 23, 2021	From v8 to v9	Changed	OPERATOR DISPLAY section
June 28, 2021	From v9 to v10	Changed	HP Engage One Pro Mounting Option AMOs section
July 9, 2021	From v10 to v11	Changed	HP Engage One Pro Bar Code Scanner section
August 9, 2021	From v11 to v12	Changed	OPERATING SYSTEM section
August 11, 2021	From v12 to v13	Changed	HP Engage One Pro VESA Hubs & cable AMOs and HP Engage One
			Pro Mounting Option AMOs sections
August 25, 2021	From v13 to v14	Changed	Integrated Camara section

title

Copyright © 2021 HP Development Company, L.P.

All rights reserved. Microsoft, Windows, Windows 7, Windows 8, and Windows 10 are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel[®], Celeron[®], Pentium[®] and CoreTM are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Linux is the registered trademark of Linus Torvalds in the U.S. and other countries. Bluetooth[®] is a registered trademark of its proprietor and used by HP Inc. under license. ENERGY STAR[®] is a registered trademark of user trademark of All States and Protection Agency.

The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.